



**GaN HEMT Pulsed Power Transistor**  
**2.7 - 3.1 GHz, 100W Peak, 500us Pulse, 10% Duty Cycle**

**Production V1**  
**23 Aug 11**

## Features

- GaN depletion mode HEMT microwave transistor
- Common source configuration
- Broadband Class AB operation
- Thermally enhanced Cu/Mo/Cu package
- RoHS Compliant
- +50V Typical Operation
- MTTF of 114 years (Channel Temperature < 200°C)

## Application

- Civilian and Military Pulsed Radar



## Product Description

The MAGX-002731-100L00 is a gold metalized matched Gallium Nitride (GaN) on Silicon Carbide RF power transistor optimized for civilian and military radar pulsed applications between 2700 - 3100 MHz. Using state of the art wafer fabrication processes, these high performance transistors provide high gain, efficiency, bandwidth, ruggedness over a wide bandwidth for today's demanding application needs. The MAGX-002731-100L00 is constructed using a thermally enhanced Cu/Mo/Cu flanged ceramic package which provides excellent thermal performance. High breakdown voltages allow for reliable and stable operation in extreme mismatched load conditions unparalleled with older semiconductor technologies.

## Typical RF Performance

Freq. (MHz)	Pin (W)	Pout (W Peak)	Gain (dB)	Id-Pk (A)	Eff (%)
2700	7	109	12	4.2	51
2900	7	112	12	4.4	51
3100	7	109	12	4.2	52

*Typical RF performance measured in M/A-COM RF test fixture. Devices tested in common source Class-AB configuration as follows: Vdd=50V, Idq=500mA (pulsed), F=2.7—3.1 GHz, Pulse=500us, Duty=10%.*

## Ordering Information

MAGX-002731-100L00      100W GaN Power Transistor  
 MAGX-002731-SB2PPR      Evaluation Fixture

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### Absolute Maximum Ratings Table (1, 2, 3)

Supply Voltage (Vdd)	+65V
Supply Voltage (Vgg)	-8 to 0V
Supply Current (Id1)	7100 mA Pk
Input Power (Pin)	+34 dBm
Absolute Max. Junction/Channel Temp	200 °C
Pulsed Power Dissipation (Pavg) at 85 °C	128W
Thermal Resistance, (Tchannel = 200 °C) VDD = 50V, IDQ = 500mA, Pout = 100W Peak (300us Pulse / 10% Duty)	0.9 °C/W
Operating Temp	-40 to +95C
Storage Temp	-65 to +150C
Mounting Temperature	See solder reflow profile
ESD Min. - Machine Model (MM)	50 V
ESD Min. - Human Body Model (HBM)	>250 V
MSL Level	MSL1

(1) Operation of this device above any one of these parameters may cause permanent damage.

(2) Channel temperature directly affects a device's MTTF. Channel temperature should be kept as low as possible to maximize lifetime.

(3) For saturated performance it recommended that the sum of  $(3 \cdot V_{dd} + \text{abs}(V_{gg})) < 175$

Parameter	Test Conditions	Symbol	Min	Typ	Max	Units
<b>DC CHARACTERISTICS</b>						
Drain-Source Leakage Current	$V_{GS} = -8V, V_{DS} = 175V$	$I_{DS}$	-	-	6	mA
Gate Threshold Voltage	$V_{DS} = 5V, I_D = 15.0mA$	$V_{GS(th)}$	-5	-3	-2	V
Forward Transconductance	$V_{DS} = 5V, I_D = 3.5mA$	$G_M$	2.5	-	-	S
<b>DYNAMIC CHARACTERISTICS</b>						
Input Capacitance	Not applicable—Input internally matched	$C_{GS}$	N/A	N/A	N/A	pF
Output Capacitance	$V_{DS} = 50V, V_{GS} = -8V, F = 1MHz$	$C_{DS}$	-	30.3	35.4	pF
Feedback Capacitance	$V_{DS} = 50V, V_{GS} = -8V, F = 1MHz$	$C_{GD}$	-	2.8	5.4	pF

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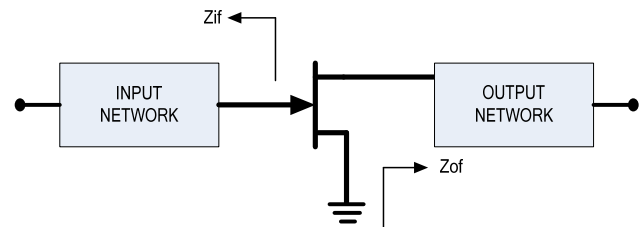
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Electrical Specifications:  $T_C = 25 \pm 5^\circ\text{C}$  (Room Ambient )

Parameter	Test Conditions	Symbol	Min	Typ	Max	Units
<b>RF FUNCTIONAL TESTS</b> $V_{dd}=50\text{V}$ , $I_{dq}=500\text{mA}$ (pulsed), $F=2.7\text{--}3.1\text{ GHz}$ , $\text{Pulse}=500\mu\text{s}$ , $\text{Duty}=10\%$						
Output Power	$P_{in} = 7\text{W Peak}$	$P_{OUT}$	100 10	105 10.5	-	W Peak W Ave
Power Gain	$P_{out} = 100\text{W Peak}$ , $10\text{W Ave}$	$G_P$	11.6	12.6	-	dB
Drain Efficiency	$P_{in} = 7\text{W Peak}$	$\eta_D$	47	53	-	%
Load Mismatch Stability	$P_{in} = 7\text{W Peak}$	VSWR-S	5:1	-	-	-
Load Mismatch Tolerance	$P_{in} = 7\text{W Peak}$	VSWR-T	10:1	-	-	-

### Test Fixture Impedance

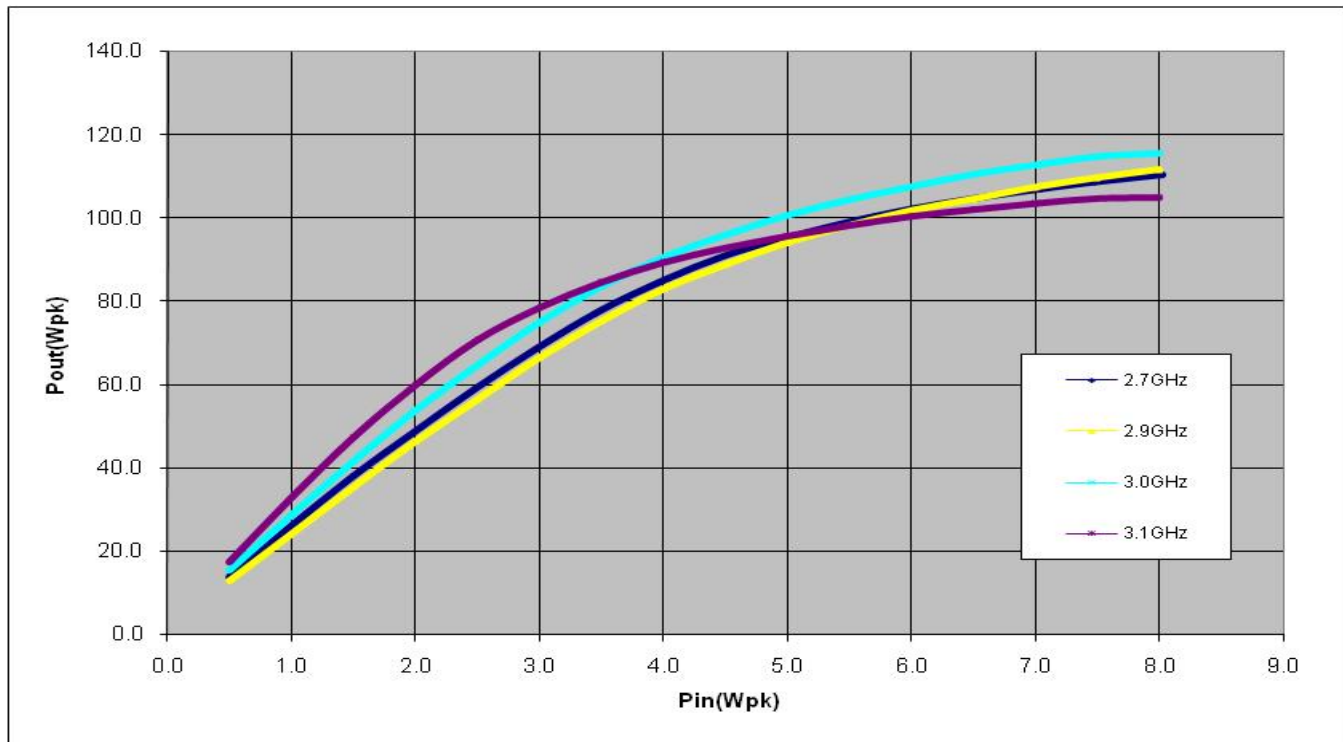
F (MHz)	$Z_{IF} (\Omega)$	$Z_{OF} (\Omega)$
2700	$3.5 - j7.5$	$3.4 + j0.4$
2900	$2.7 - j5.3$	$4.7 - j0.8$
3100	$2.0 - j4.1$	$2.5 - j1.7$



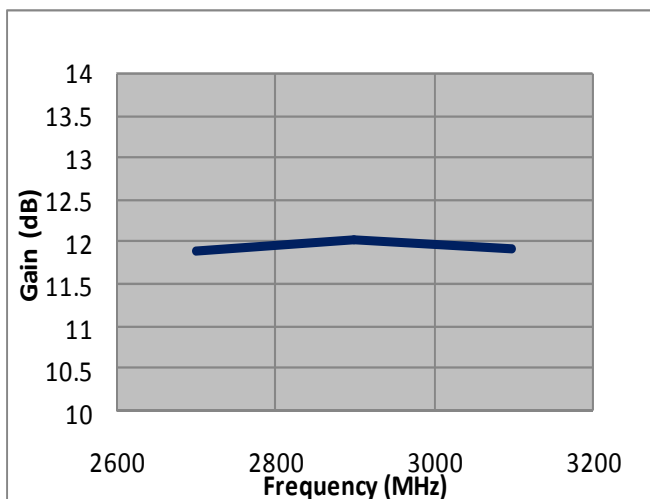
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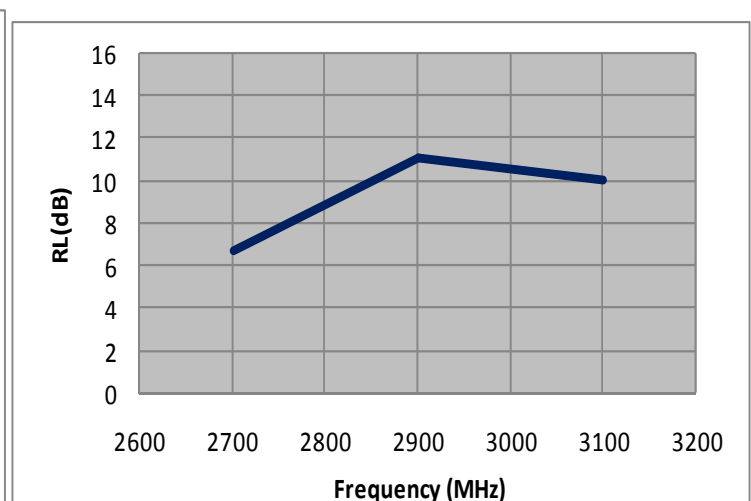
**RF Power Transfer Curve at 50V Drain Bias, Idq=0.5A**  
**Output Power vs. Input Power**



**Gain vs. Frequency**  
 50V Drain Bias, Idq=0.5A



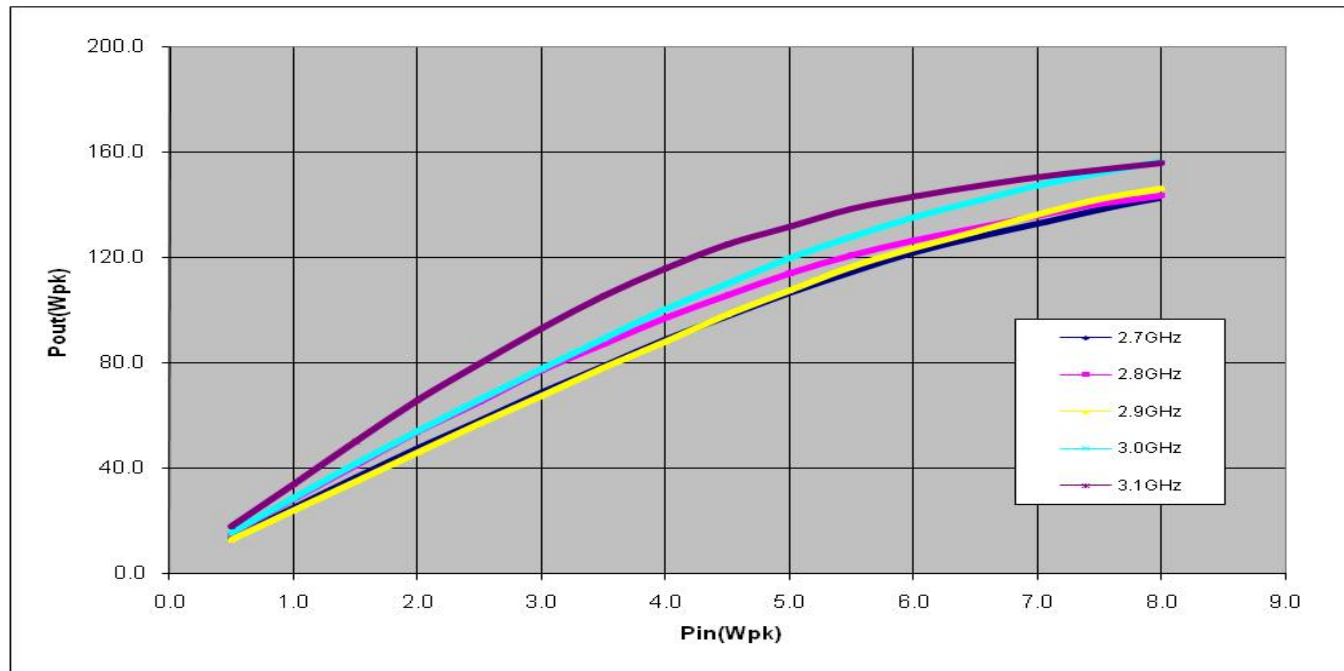
**Return Loss vs. Frequency**  
 50V Drain Bias, Idq=0.5A



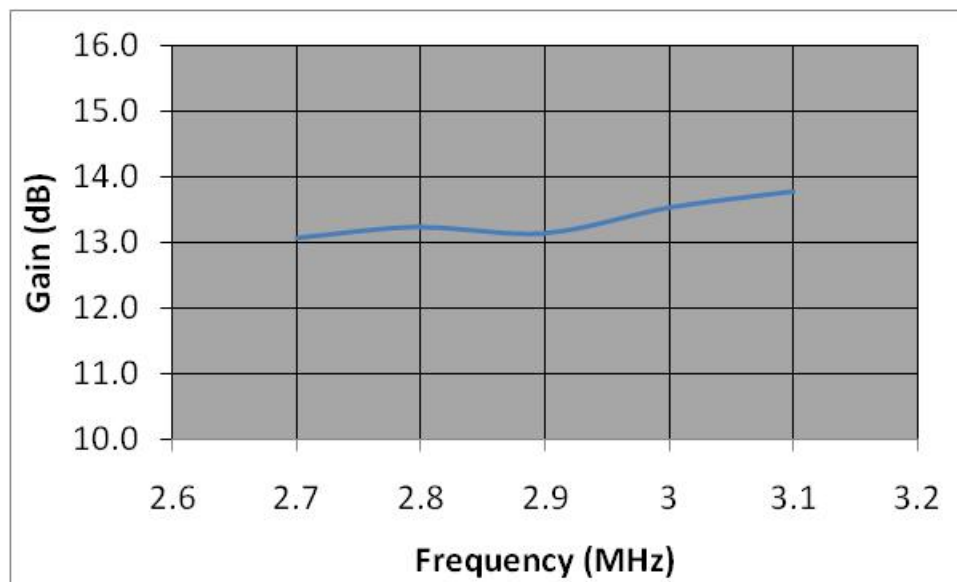
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**RF Power Transfer Curve at 65V Drain Bias, Idq=0.5A**  
**Output Power vs. Input Power**



**Gain vs. Frequency**  
 65V Drain Bias, Idq=0.5A



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[illegible]

Note: A dwg circuit drawing is available upon request

ASSEMBLY VIEW

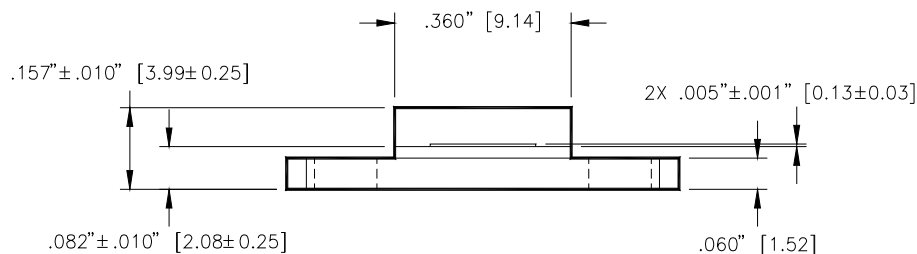
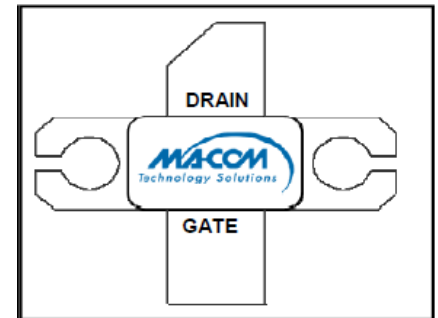
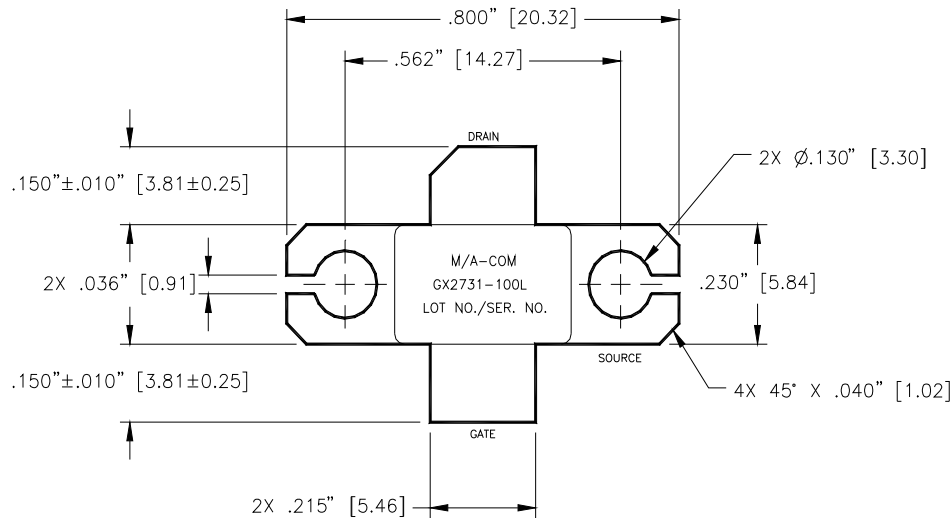
Labels and components shown in the assembly view:

- CHIP CAPACITOR .1uF 100 VOLT C2,C4
- CHIP CAPACITOR 22pF ATC100A
- CHIP CAPACITOR 1uF 100 VOLT
- GROUND SHIM G1,G2,G3,G4,G5,G6
- ELECTROLYTIC CAPACITOR 100uF 160 VOLT
- CHIP CAPACITOR 47pF ATC100A C1,C6
- NO. 22 AWG X .83" SOLID COPPER WIRE OVER QUARTER-WAVE ELEMENT
- BOARD CARRIER 73050257-17
- TRANSISTOR CLAMP 74250125-55
- TRANSISTOR CARRIER 73050256-23
- BOARD CARRIER 73050257-15
- HEATSINK 73050255-23
- SMA CONNECTOR M/A-COM 2052-5636-02 J1,J2
- PC BOARDS 11 OHM 1/2 WATT
- CARBON RESISTOR 11 OHM 1/2 WATT
- FEMALE BANANA JACK, J3,J4,J5,J6
- J3 BLK
- J4 RED
- J5 RED
- J6 BLK
- G1,G2
- G3
- G4,G5
- C3
- C4
- C5
- C6
- C7
- L1
- R1
- M/A-COM (MTS)
- TFMAGX-002731-100L00

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## Outline Drawings



Unless otherwise noted, tolerances are inches  $\pm 0.005$  [millimeters  $\pm 0.13\text{mm}$ ]

## CORRECT DEVICE SEQUENCING

### TURNING THE DEVICE ON

1. Set  $V_{GS}$  to the pinch-off ( $V_P$ ), typically -5V
2. Turn on  $V_{DS}$  to nominal voltage (50V)
3. Increase  $V_{GS}$  until the  $I_{DS}$  current is reached
4. Apply RF power to desired level

### TURNING THE DEVICE OFF

1. Turn the RF power off
2. Decrease  $V_{GS}$  down to  $V_P$
3. Decrease  $V_{DS}$  down to 0V
4. Turn off  $V_{GS}$

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